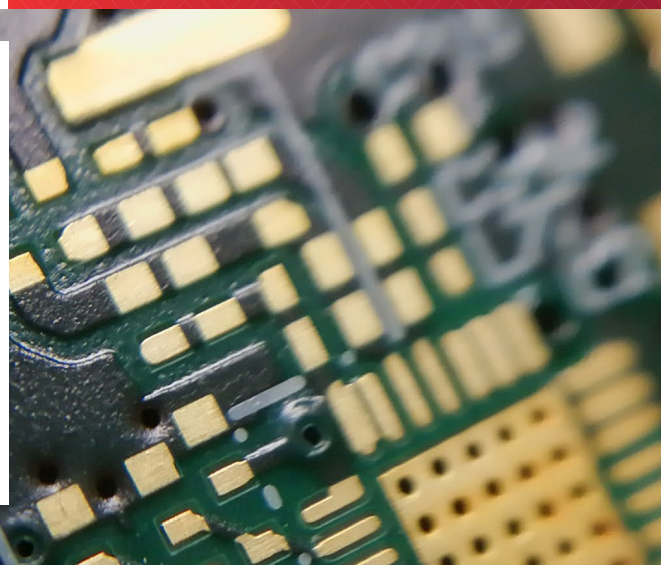


## Open-Molded Plastic Packages (OmPP)

QP Technologies announces the exclusive Open-molded Plastic Package (OmPP)™ for your packaging needs. From prototype to production volumes, these premolded QFN packages, created by QP Technologies, provide a high-quality, fast solution for your assembly needs.



### Advantages:

- Larger die paddle area - supports larger die and ground bonds per given body size
- RoHS- and REACH-compliant “Green” molding compound
- Gold plated
- Superior bondability
- Custom body sizes and counts available



### Premolded Packages offer Flexibility

QP Technologies’ premolded packages come in a variety of sizes. They are available from 3x3mm to 12x12mm body size with lead pitch sizes ranging from 0.80mm to 0.40mm. Covers or lids are also available for air cavity applications.

QP Technologies has been a standard part of your product development process for over 15 years, providing Open Cavity Plastic Package (OCP), custom packaging and assembly solutions. The Open-molded Plastic Packages (OmPP) solution offers production-quality premolded packages, flexibility and rapid delivery to meet your needs.

QP Technologies offers a turnkey assembly solution including:

- |                    |  |
|--------------------|--|
| • Wafer Dicing     | • Backgrinding                               |
| • Wire Bonding     | • Complete Assembly                          |
| • Custom Packaging | • Patented Open Cavity Plastic Package (OCP) |

As a leader in quick-turn assembly, QP Technologies provides dependable customer service with every order. The company also provides application engineering support to optimize your assembly process. Whether bondability, dispensing materials or package customization, the QP Technologies staff has the expertise to assist you with any project.

Samples are available upon request. Please visit [www.icproto.com](http://www.icproto.com) or contact us at (858) 674-4676.